

MOSFET

600V CoolMOS™ CE Power Transistor

CoolMOS™ is a revolutionary technology for high voltage power MOSFETs, designed according to the superjunction (SJ) principle and pioneered by Infineon Technologies. CoolMOS™ CE is a price-performance optimized platform enabling to target cost sensitive applications in Consumer and Lighting markets by still meeting highest efficiency standards. The new series provides all benefits of a fast switching Superjunction MOSFET while not sacrificing ease of use and offering the best cost down performance ratio available on the market.

Features

- Extremely low losses due to very low FOM $R_{DS(on)} \cdot Q_g$ and E_{oss}
- Very high commutation ruggedness
- Easy to use/drive
- Pb-free plating, Halogen free mold compound
- Qualified for standard grade applications

Applications

PFC stages, hard switching PWM stages and resonant switching stages for e.g. PC Silverbox, Adapter, LCD & PDP TV and indoor lighting.

Please note: For MOSFET paralleling the use of ferrite beads on the gate or separate totem poles is generally recommended.

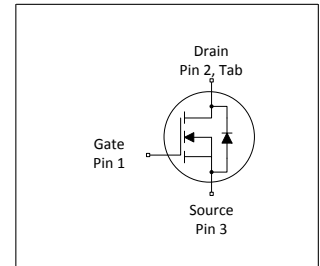
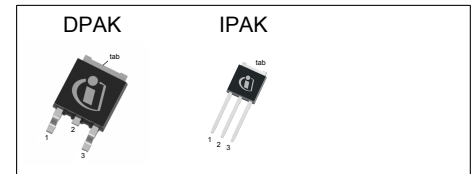


Table 1 Key Performance Parameters

Parameter	Value	Unit
$V_{DS} @ T_{j,max}$	650	V
$R_{DS(on),max}$	1000	mΩ
I_d	6.8	A
$Q_{g,typ}$	13	nC
$I_{D,pulse}$	12	A
$E_{oss}@400V$	1.3	μJ

Type / Ordering Code	Package	Marking	Related Links
IPD60R1K0CE	PG-TO 252	60S1K0CE	see Appendix A
IPU60R1K0CE	PG-TO 251		

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1 Maximum ratings

at $T_j = 25^\circ\text{C}$, unless otherwise specified

Table 2 Maximum ratings

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current ¹⁾	I_D	-	-	6.8 4.3	A	$T_C=25^\circ\text{C}$ $T_C=100^\circ\text{C}$
Pulsed drain current ²⁾	$I_{D,pulse}$	-	-	12	A	$T_C=25^\circ\text{C}$
Avalanche energy, single pulse	E_{AS}	-	-	46	mJ	$I_D=0.8\text{A}$; $V_{DD}=50\text{V}$; see table 11
Avalanche energy, repetitive	E_{AR}	-	-	0.13	mJ	$I_D=0.8\text{A}$; $V_{DD}=50\text{V}$; see table 11
Avalanche current, repetitive	I_{AR}	-	-	0.8	A	-
MOSFET dv/dt ruggedness	dv/dt	-	-	50	V/ns	$V_{DS}=0\dots480\text{V}$
Gate source voltage (static)	V_{GS}	-20	-	20	V	static;
Gate source voltage (dynamic)	V_{GS}	-30	-	30	V	AC ($f>1\text{ Hz}$)
Power dissipation TO-251, TO-252	P_{tot}	-	-	61	W	$T_C=25^\circ\text{C}$
Storage temperature	T_{stg}	-40	-	150	$^\circ\text{C}$	-
Operating junction temperature	T_j	-40	-	150	$^\circ\text{C}$	-
Continuous diode forward current	I_S	-	-	4.8	A	$T_C=25^\circ\text{C}$
Diode pulse current ²⁾	$I_{S,pulse}$	-	-	12	A	$T_C=25^\circ\text{C}$
Reverse diode dv/dt ³⁾	dv/dt	-	-	15	V/ns	$V_{DS}=0\dots400\text{V}$, $I_{SD}\leq I_S$, $T_j=25^\circ\text{C}$ see table 9
Maximum diode commutation speed	di/dt	-	-	500	A/ μs	$V_{DS}=0\dots400\text{V}$, $I_{SD}\leq I_S$, $T_j=25^\circ\text{C}$ see table 9

2 Thermal characteristics

Table 3 Thermal characteristics TO-251, TO252

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	-	2.06	$^\circ\text{C/W}$	-
Thermal resistance, junction - ambient	R_{thJA}	-	-	62	$^\circ\text{C/W}$	lead
Soldering temperature, wavesoldering only allowed at leads	T_{sold}	-	-	260	$^\circ\text{C}$	1.6mm (0.063 in.) from case for 10s

¹⁾ Limited by $T_{j,max}$. Maximum duty cycle $D=0.50$

²⁾ Pulse width t_p limited by $T_{j,max}$

³⁾ Identical low side and high side switch with identical R_G

3 Electrical characteristics

at $T_j=25^\circ\text{C}$, unless otherwise specified

Table 4 Static characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	600	-	-	V	$V_{GS}=0V$, $I_D=0.25mA$
Gate threshold voltage	$V_{(GS)th}$	2.5	3.0	3.5	V	$V_{DS}=V_{GS}$, $I_D=0.13mA$
Zero gate voltage drain current	I_{DSS}	-	-	1	μA	$V_{DS}=600$, $V_{GS}=0V$, $T_j=25^\circ\text{C}$ $V_{DS}=600$, $V_{GS}=0V$, $T_j=150^\circ\text{C}$
Gate-source leakage current	I_{GSS}	-	-	100	nA	$V_{GS}=20V$, $V_{DS}=0V$
Drain-source on-state resistance	$R_{DS(on)}$	-	0.86 2.22	1.00	Ω	$V_{GS}=10V$, $I_D=1.5A$, $T_j=25^\circ\text{C}$ $V_{GS}=10V$, $I_D=1.5A$, $T_j=150^\circ\text{C}$
Gate resistance	R_G	-	16	-	Ω	$f=1MHz$, open drain

Table 5 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance	C_{iss}	-	280	-	pF	$V_{GS}=0V$, $V_{DS}=100V$, $f=1MHz$
Output capacitance	C_{oss}	-	21	-	pF	$V_{GS}=0V$, $V_{DS}=100V$, $f=1MHz$
Effective output capacitance, energy related ¹⁾	$C_{o(er)}$	-	14	-	pF	$V_{GS}=0V$, $V_{DS}=0...480V$
Effective output capacitance, time related ²⁾	$C_{o(tr)}$	-	57	-	pF	$I_D=\text{constant}$, $V_{GS}=0V$, $V_{DS}=0...480V$
Turn-on delay time	$t_{d(on)}$	-	10	-	ns	$V_{DD}=400V$, $V_{GS}=10V$, $I_D=1.9A$, $R_G=12.2\Omega$; see table 10
Rise time	t_r	-	8	-	ns	$V_{DD}=400V$, $V_{GS}=10V$, $I_D=1.9A$, $R_G=12.2\Omega$; see table 10
Turn-off delay time	$t_{d(off)}$	-	60	-	ns	$V_{DD}=400V$, $V_{GS}=10V$, $I_D=1.9A$, $R_G=12.2\Omega$; see table 10
Fall time	t_f	-	13	-	ns	$V_{DD}=400V$, $V_{GS}=10V$, $I_D=1.9A$, $R_G=12.2\Omega$; see table 10

Table 6 Gate charge characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	Q_{gs}	-	1.5	-	nC	$V_{DD}=480V$, $I_D=1.9A$, $V_{GS}=0$ to $10V$
Gate to drain charge	Q_{gd}	-	6.5	-	nC	$V_{DD}=480V$, $I_D=1.9A$, $V_{GS}=0$ to $10V$
Gate charge total	Q_g	-	13	-	nC	$V_{DD}=480V$, $I_D=1.9A$, $V_{GS}=0$ to $10V$
Gate plateau voltage	$V_{plateau}$	-	5.4	-	V	$V_{DD}=480V$, $I_D=1.9A$, $V_{GS}=0$ to $10V$

¹⁾ $C_{o(er)}$ is a fixed capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 80% $V_{(BR)DSS}$

²⁾ $C_{o(tr)}$ is a fixed capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 80% $V_{(BR)DSS}$

Table 7 Reverse diode characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode forward voltage	V_{SD}	-	0.9	-	V	$V_{GS}=0V$, $I_F=1.9A$, $T_J=25^{\circ}C$
Reverse recovery time	t_{rr}	-	220	-	ns	$V_R=400V$, $I_F=1.9A$, $di_F/dt=100A/\mu s$; see table 9
Reverse recovery charge	Q_{rr}	-	1.5	-	μC	$V_R=400V$, $I_F=1.9A$, $di_F/dt=100A/\mu s$; see table 9
Peak reverse recovery current	I_{rrm}	-	12	-	A	$V_R=400V$, $I_F=1.9A$, $di_F/dt=100A/\mu s$; see table 9

4 Electrical characteristics diagrams

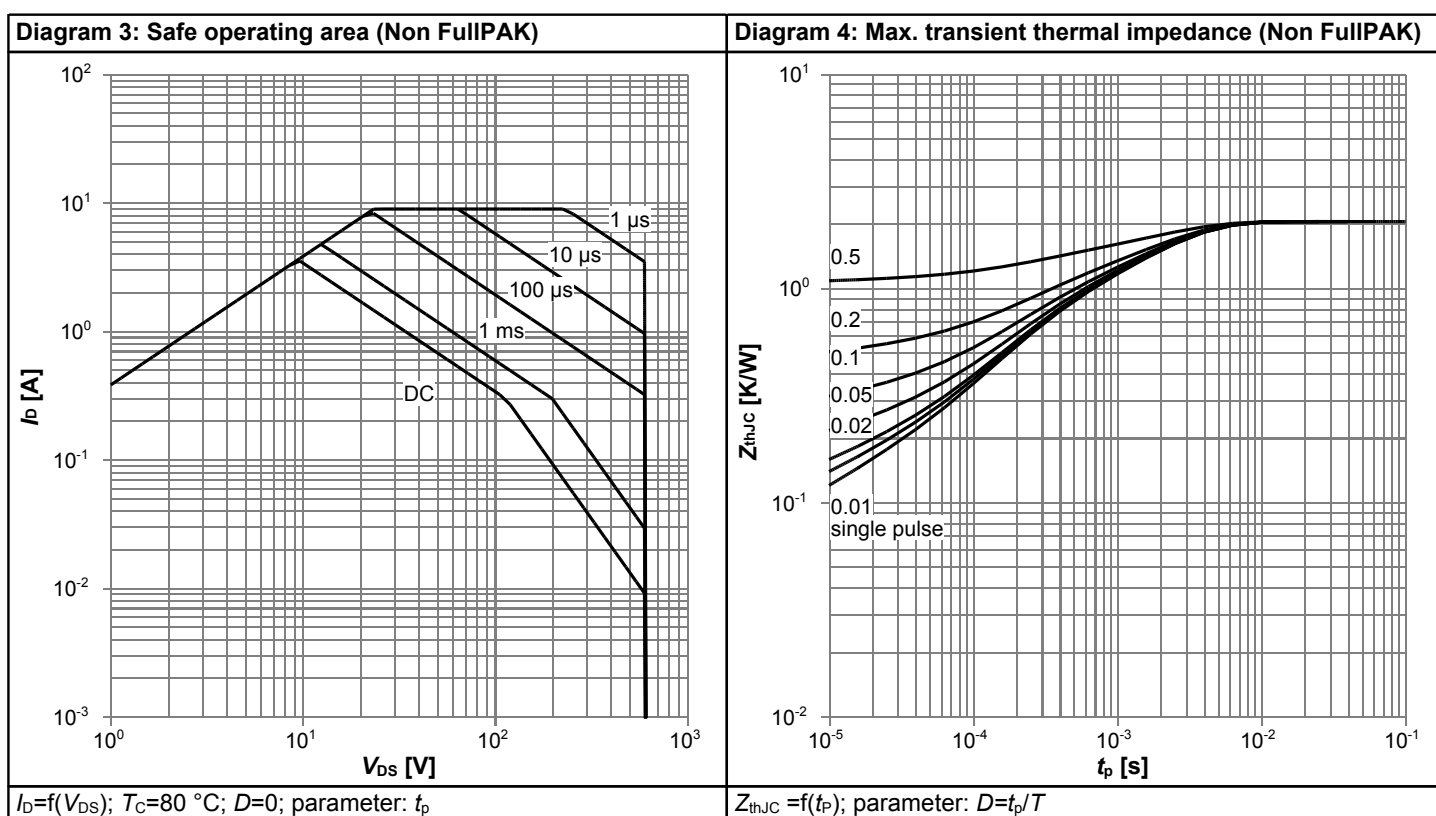
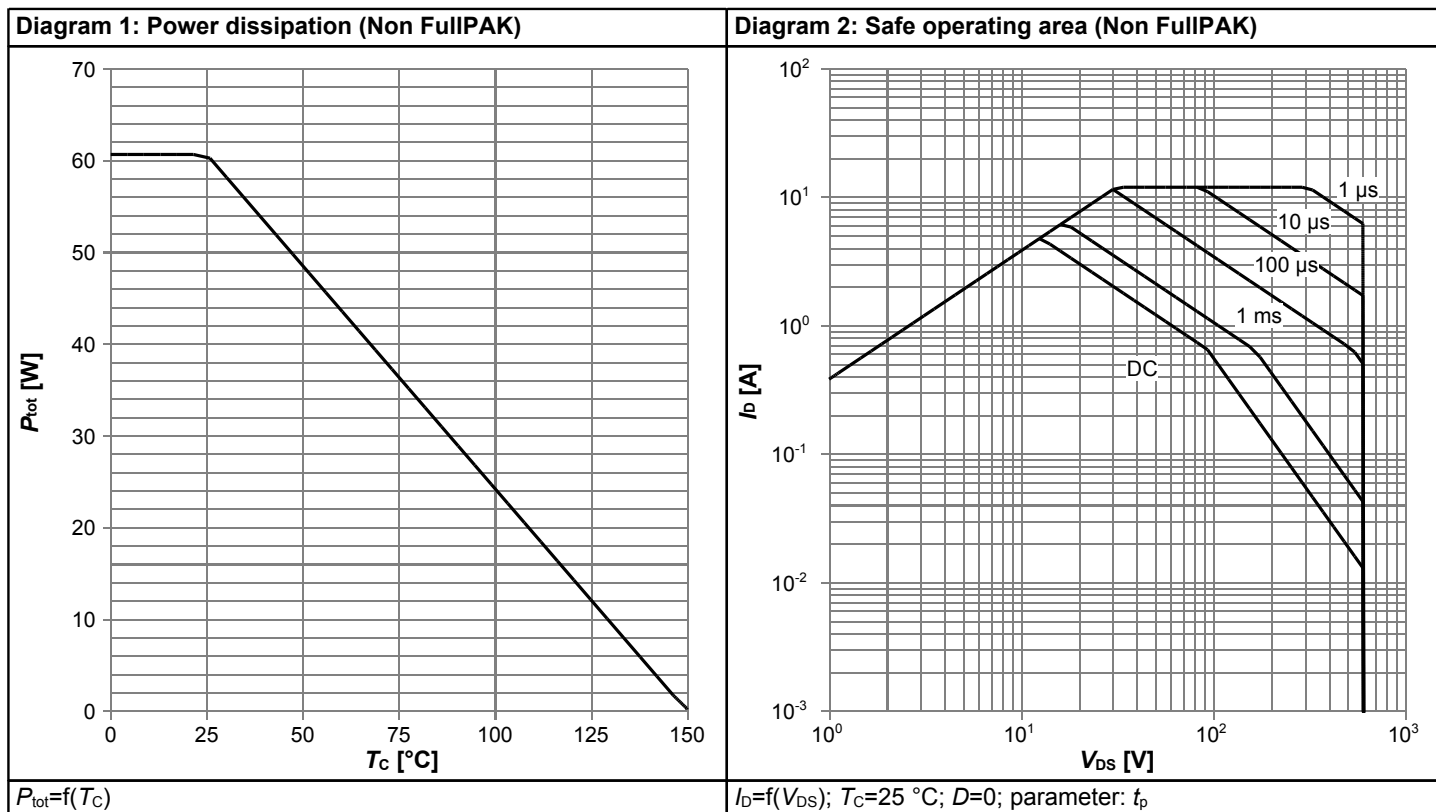
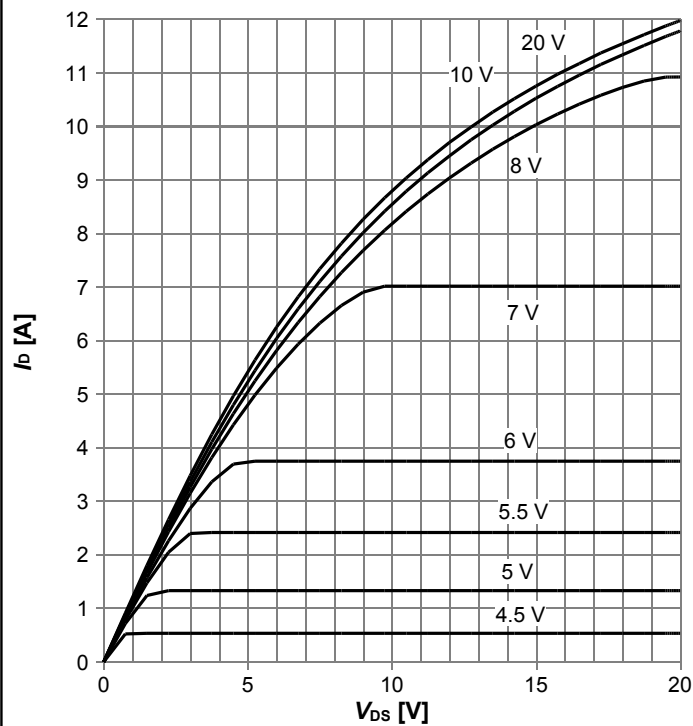
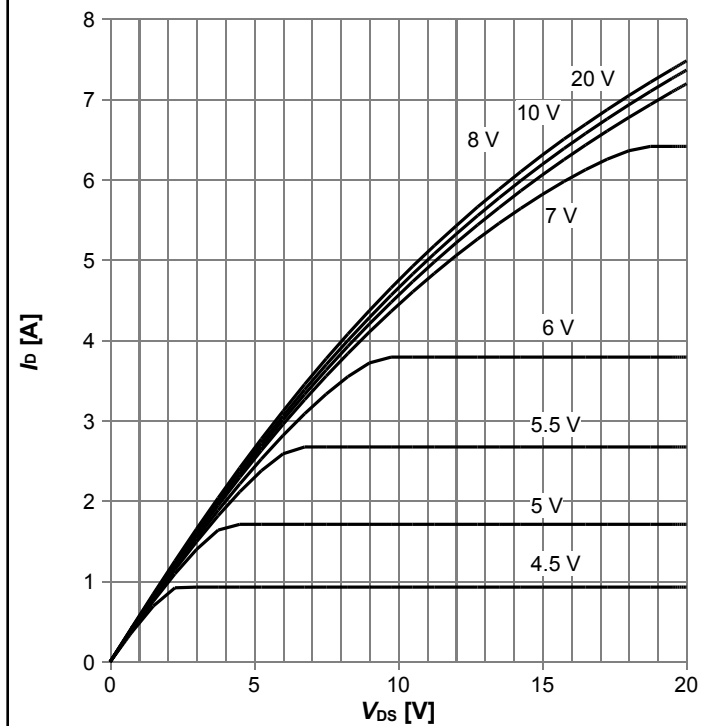


Diagram 5: Typ. output characteristics



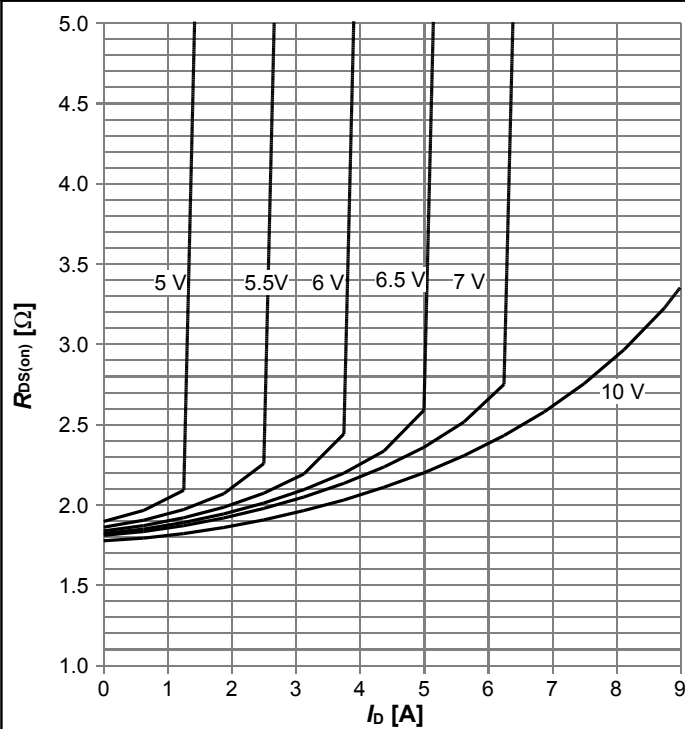
$I_D = f(V_{DS})$; $T_j = 25\text{ °C}$; parameter: V_{GS}

Diagram 6: Typ. output characteristics



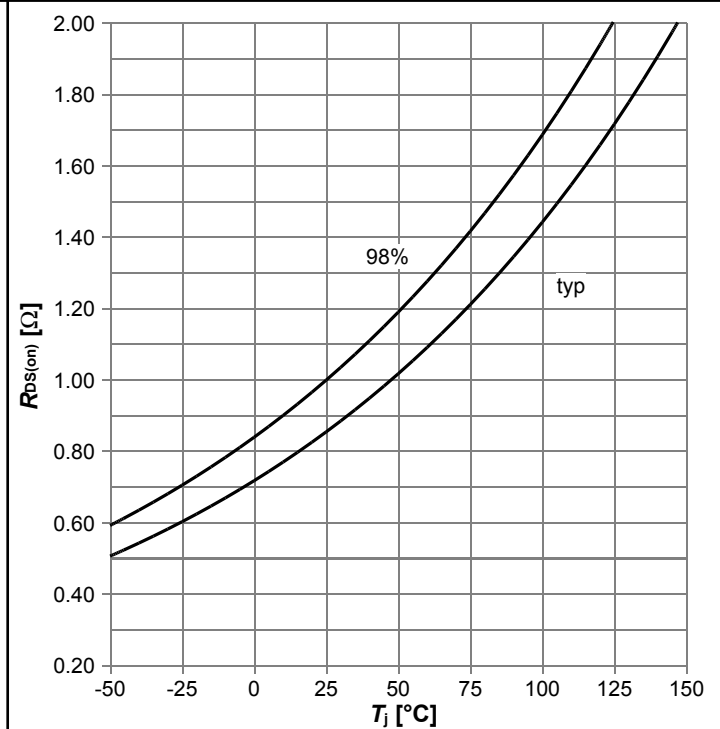
$I_D = f(V_{DS})$; $T_j = 125\text{ °C}$; parameter: V_{GS}

Diagram 7: Typ. drain-source on-state resistance



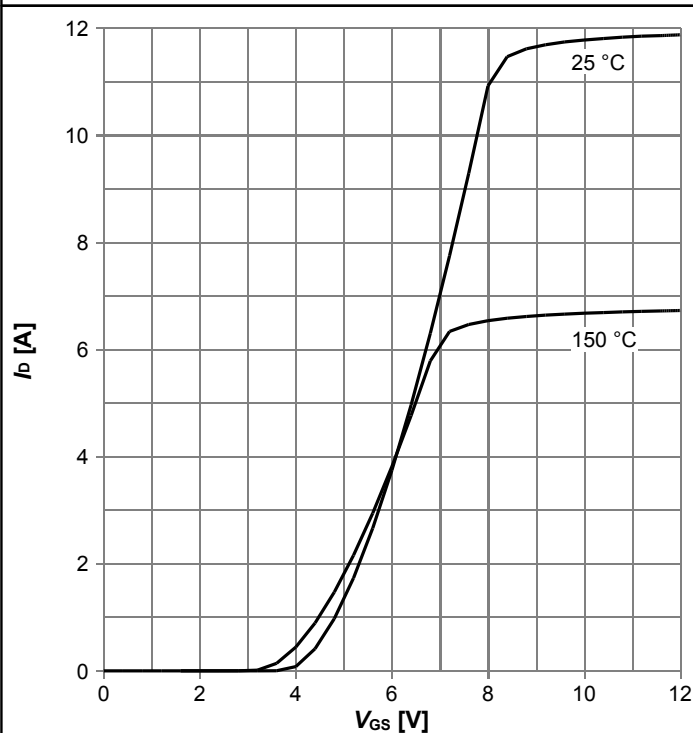
$R_{DS(on)} = f(I_D)$; $T_j = 125\text{ °C}$; parameter: V_{GS}

Diagram 8: Drain-source on-state resistance



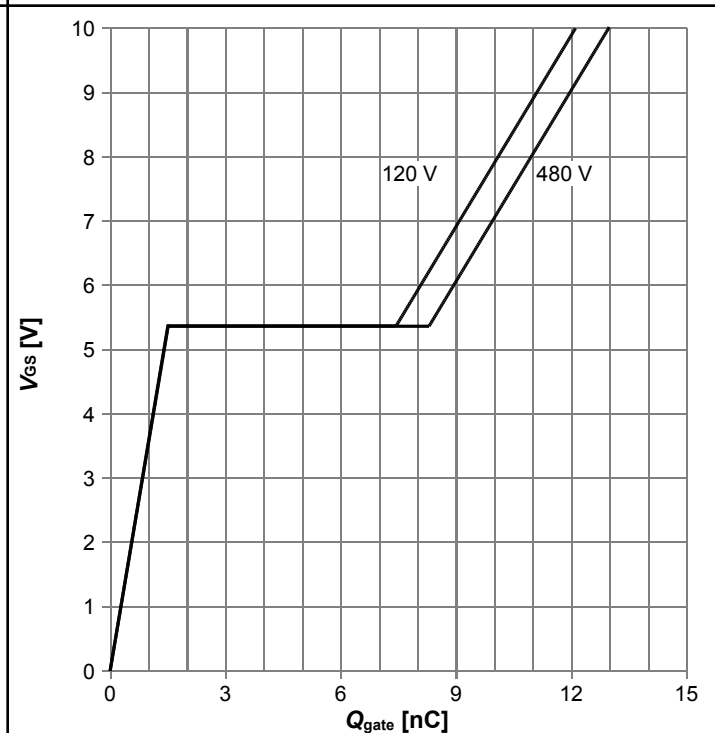
$R_{DS(on)} = f(T_j)$; $I_D = 1.5\text{ A}$; $V_{GS} = 10\text{ V}$

Diagram 9: Typ. transfer characteristics



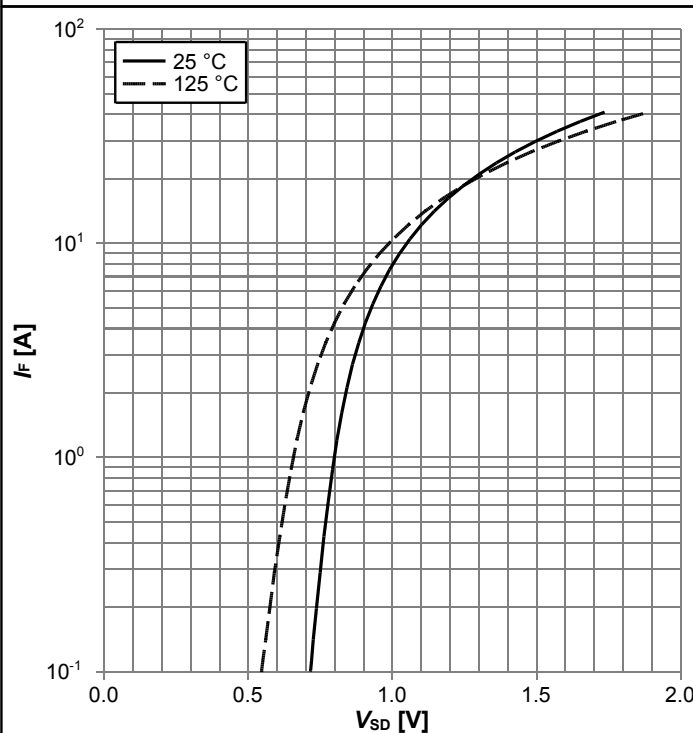
$I_D = f(V_{GS})$; $V_{DS} = 20$ V; parameter: T_j

Diagram 10: Typ. gate charge



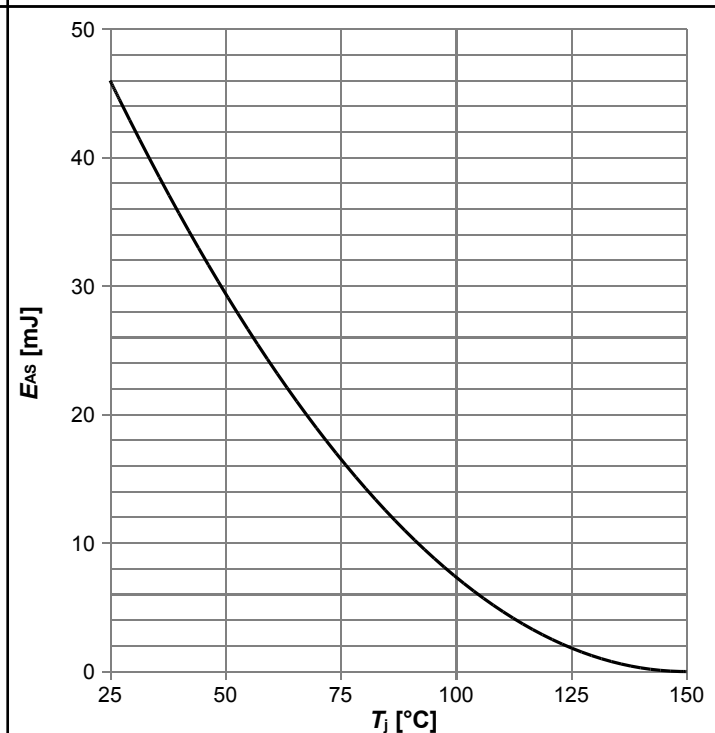
$V_{GS} = f(Q_{gate})$; $I_D = 1.9$ A pulsed; parameter: V_{DD}

Diagram 11: Forward characteristics of reverse diode



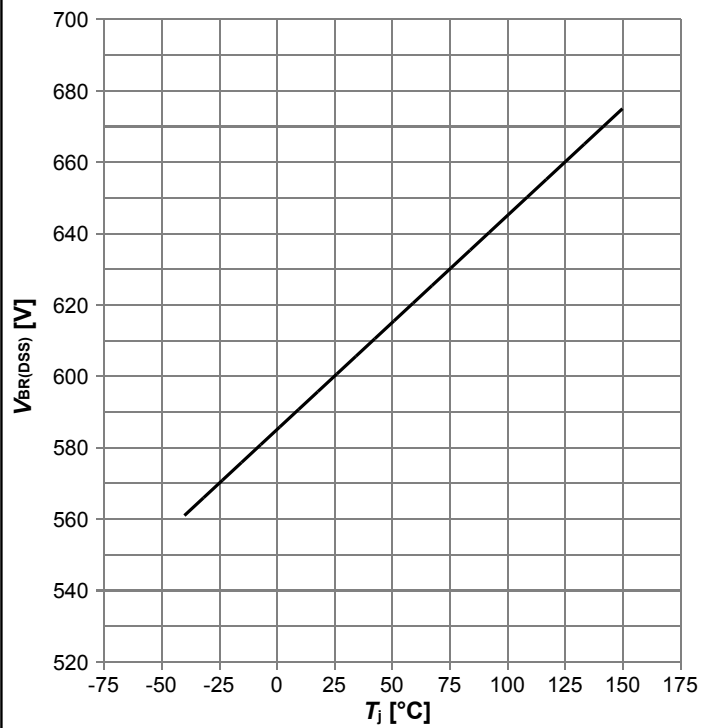
$I_F = f(V_{SD})$; parameter: T_j

Diagram 12: Avalanche energy



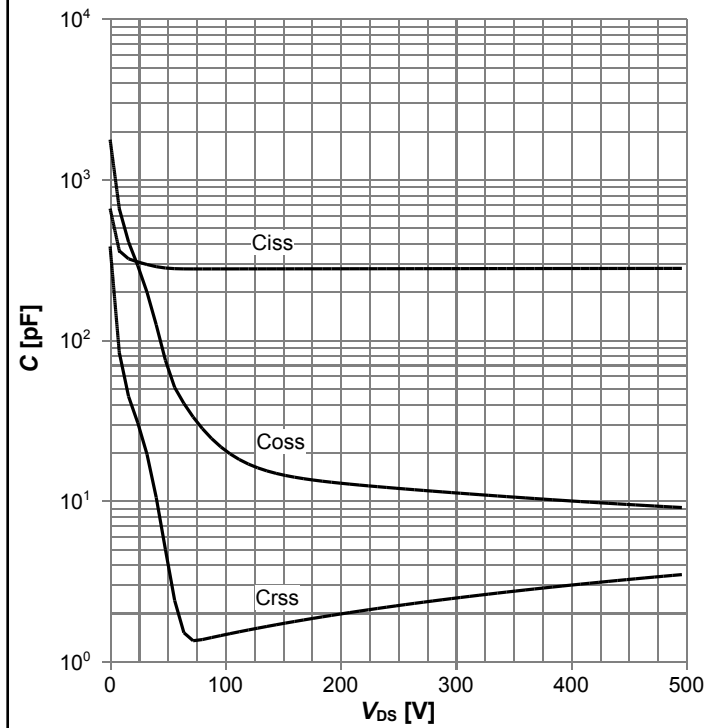
$E_{AS} = f(T_j)$; $I_D = 0.8$ A; $V_{DD} = 50$ V

Diagram 13: Drain-source breakdown voltage



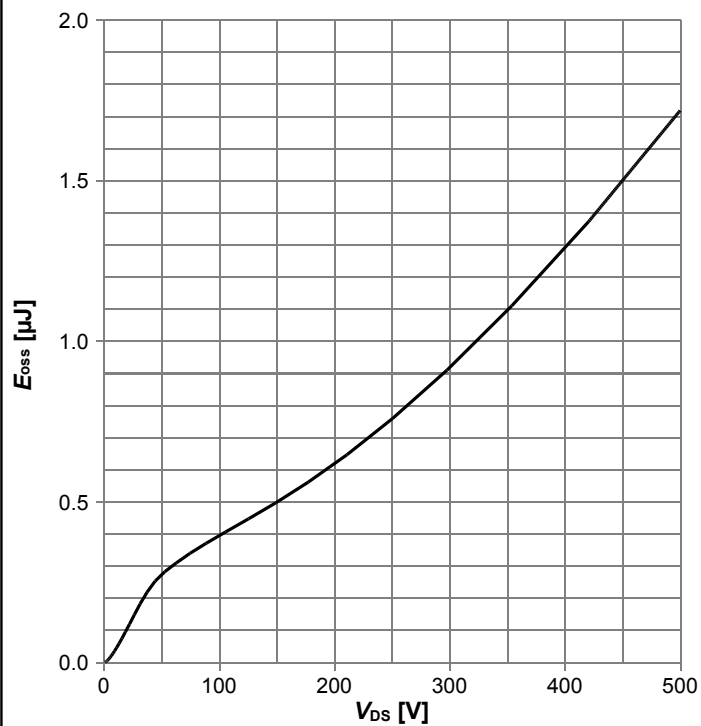
$V_{BR(DSS)} = f(T_j); I_D = 0.25 \text{ mA}$

Diagram 14: Typ. capacitances



$C = f(V_{DS}); V_{GS} = 0 \text{ V}; f = 1 \text{ MHz}$

Diagram 15: Typ. Coss stored energy



$E_{oss} = f(V_{DS})$

5 Test Circuits

Table 8 Diode characteristics

Test circuit for diode characteristics	Diode recovery waveform
 $R_{g1} = R_{g2}$	 $t_{tr} = t_F + t_S$ $Q_{tr} = Q_F + Q_S$

Table 9 Switching times

Switching times test circuit for inductive load	Switching times waveform
	 $t_{d(on)}$, t_r, $t_{d(off)}$, t_f, t_{on}, t_{off}

Table 10 Unclamped inductive load

Unclamped inductive load test circuit	Unclamped inductive waveform
	 $V_{(BR)DS}$

6 Package Outlines

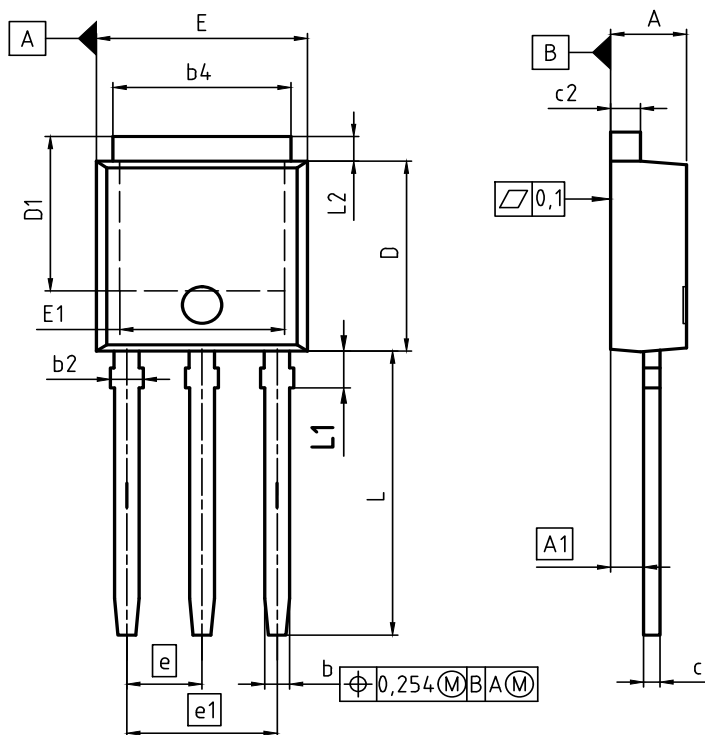


*) mold flash not included

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.16	2.41	0.085	0.095
A1	0.00	0.15	0.000	0.006
b	0.64	0.89	0.025	0.035
b2	0.65	1.15	0.026	0.045
b3	5.00	5.50	0.197	0.217
c	0.46	0.60	0.018	0.024
c2	0.46	0.98	0.018	0.039
D	5.97	6.22	0.235	0.245
D1	5.02	5.84	0.198	0.230
E	6.40	6.73	0.252	0.265
E1	4.70	5.60	0.185	0.220
e	2.29 (BSC)		0.090 (BSC)	
e1	4.57 (BSC)		0.180 (BSC)	
N	3		3	
H	9.40	10.48	0.370	0.413
L	1.18	1.70	0.046	0.067
L3	0.90	1.25	0.035	0.049
L4	0.51	1.00	0.020	0.039
F1	10.60		0.417	
F2	6.40		0.252	
F3	2.20		0.087	
F4	5.80		0.228	
F5	5.76		0.227	
F6	1.20		0.047	

DOCUMENT NO. Z8B00003328
SCALE 0 2.0 4mm
EUROPEAN PROJECTION
ISSUE DATE 01-09-2015
REVISION 05

Figure 1 Outline PG-TO 252, dimensions in mm/inches



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.16	2.41	0.085	0.095
A1	0.90	1.14	0.035	0.045
b	0.64	0.89	0.025	0.035
b2	0.65	1.15	0.026	0.045
b4	4.95	5.50	0.195	0.217
c	0.46	0.60	0.018	0.024
c2	0.46	0.89	0.018	0.035
D	5.97	6.22	0.235	0.245
D1	5.04	5.77	0.198	0.227
E	6.35	6.73	0.250	0.265
E1	4.70	5.21	0.185	0.205
e	2.29		0.090	
e1	4.57		0.180	
N	3		3	
L	8.89	9.65	0.350	0.380
L1	0.85	2.29	0.033	0.090
L2	0.89	1.37	0.035	0.054

DOCUMENT NO. Z8B00003330
SCALE
EUROPEAN PROJECTION
ISSUE DATE 31-08-2015
REVISION 04

Figure 2 Outline PG-TO 251, dimensions in mm/inches

7 Appendix A

Table 11 Related Links

- IFX CoolMOS™ CE Webpage: www.infineon.com
- IFX CoolMOS™ CE application note: www.infineon.com
- IFX CoolMOS™ CE simulation model: www.infineon.com
- IFX Design tools: www.infineon.com

Revision History

IPD60R1K0CE, IPU60R1K0CE

Revision: 2016-03-31

Previous Revision

Date	Subjects (major changes since last revision)
2014-09-25	Release of final version
2015-11-17	Updated to qualified for standard grade & updated package drawing
2016-03-31	Modified Id, Rthjc. Modified SOA, Zthjc curves

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81726 München, Germany
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